



Material Content Data Sheet



Sales Product Name	BB 857 H7902			Issued		29. August 2013		
MA#	MA000770726							
Package	PG-SCD80-2-1			Weight*		1.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		16	
	noble metal	gold	7440-57-5	0.003	0.16		1589	
	inorganic material	silicon	7440-21-3	0.026	1.36	1.52	13570	15175
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		396	
	non noble metal	chromium	7440-47-3	0.002	0.12		1190	
	non noble metal	copper	7440-50-8	0.744	39.49	39.66	394867	396532
wire	non noble metal	copper	7440-50-8	0.002	0.11	0.11	1132	1132
encapsulation	organic material	carbon black	1333-86-4	0.010	0.52		5224	
	plastics	epoxy resin	-	0.167	8.88		88808	
	inorganic material	silicondioxide	60676-86-0	0.807	42.83	52.23	428369	522401
leadfinish	non noble metal	tin	7440-31-5	0.036	1.91	1.91	19103	19103
plating	noble metal	silver	7440-22-4	0.086	4.57	4.57	45657	45657
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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